

P-Channel Enhancement Mode MOSFET

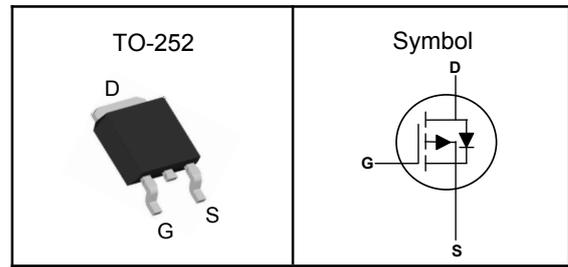
Features

- Advanced trench cell design
- Low Thermal Resistance
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Motor drivers
- DC - DC Converter

Pin Description



V_{DSS}	-40	V
$R_{DS(ON)-Typ}$	14	m Ω
I_D	-40	A

Absolute Maximum Ratings ($T_J=25^{\circ}C$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	-40	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
$I_{DM}^{①}$	Pulse Drain Current Tested	-160	A
I_D	Continuous Drain Current	$T_c=25^{\circ}C$	A
P_D	Maximum Power Dissipation	$T_c=25^{\circ}C$	W
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.5mH	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	16	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.25	$^{\circ}C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 $^{\circ}C$.

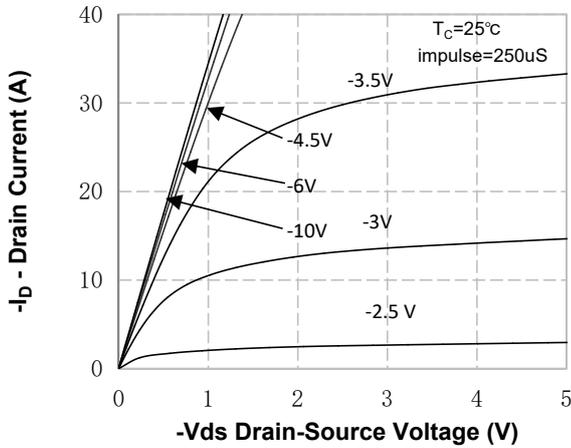
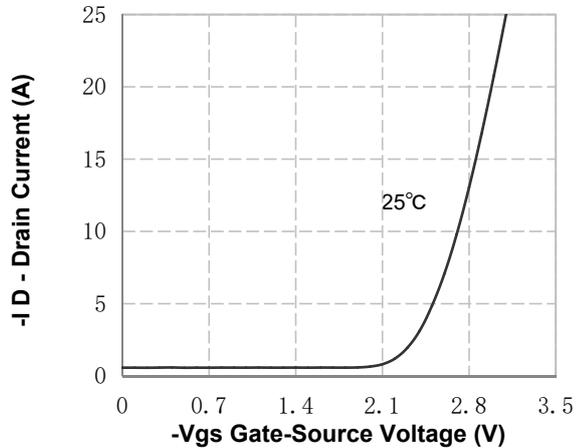
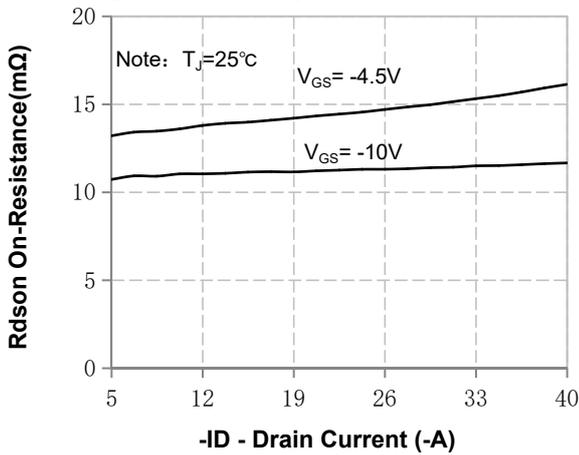
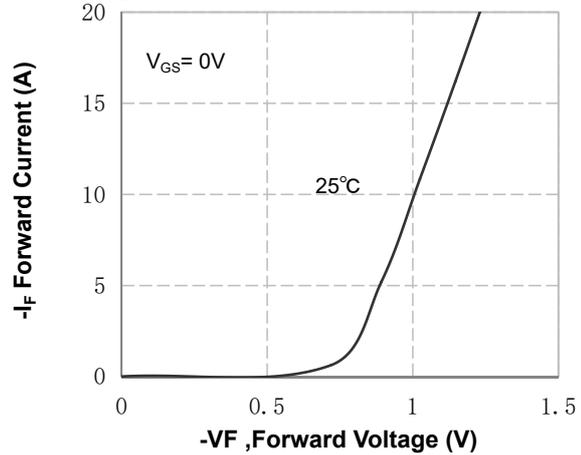
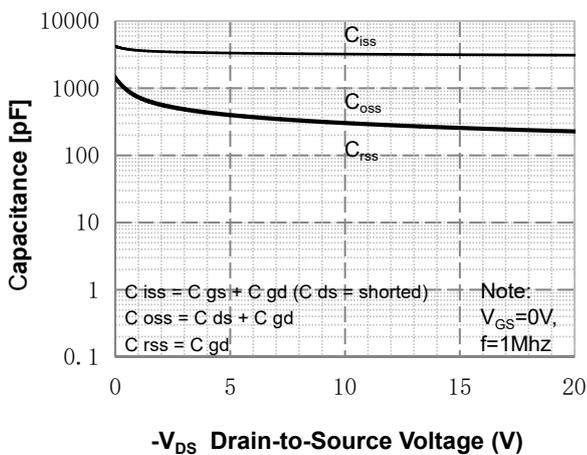
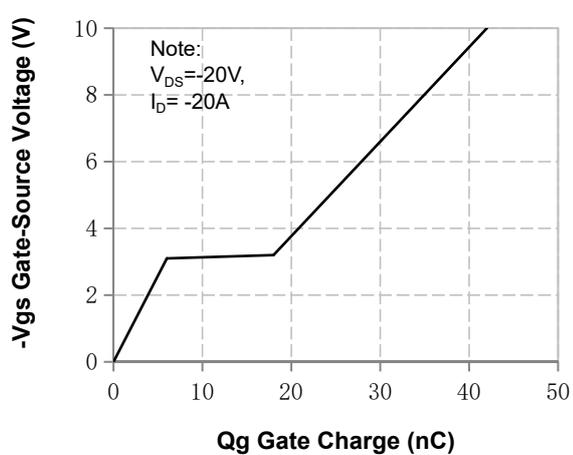
Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

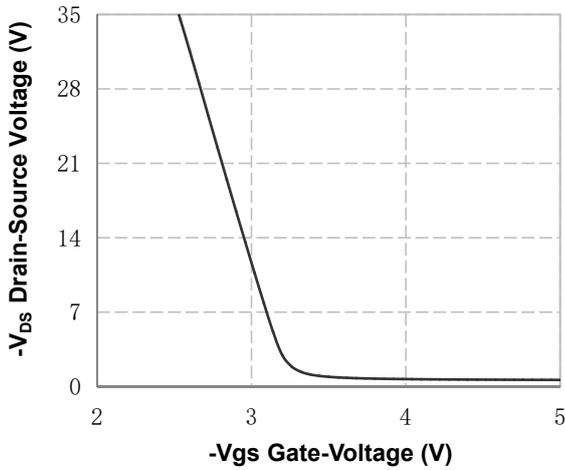
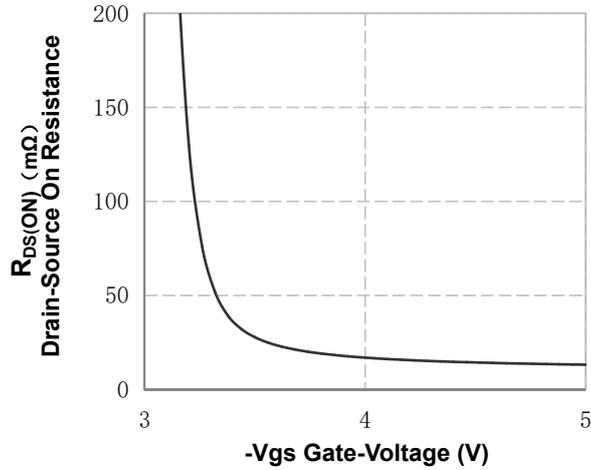
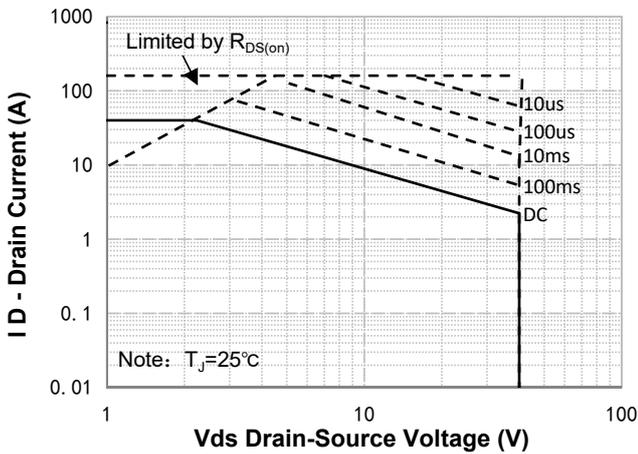
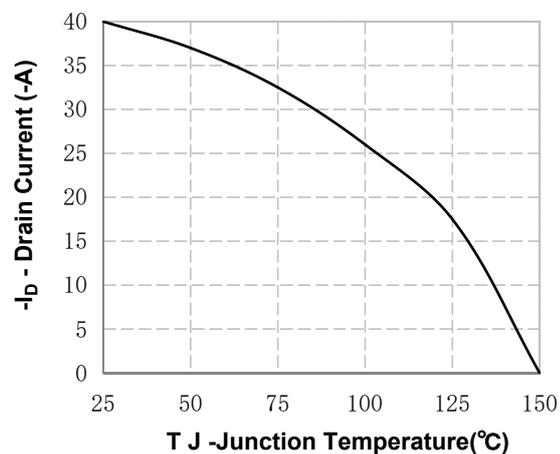
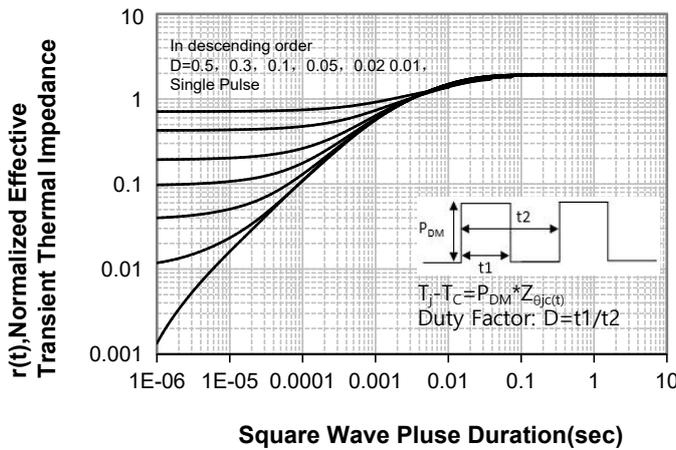
**P-Channel Enhancement Mode MOSFET****Electrical Characteristics** ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

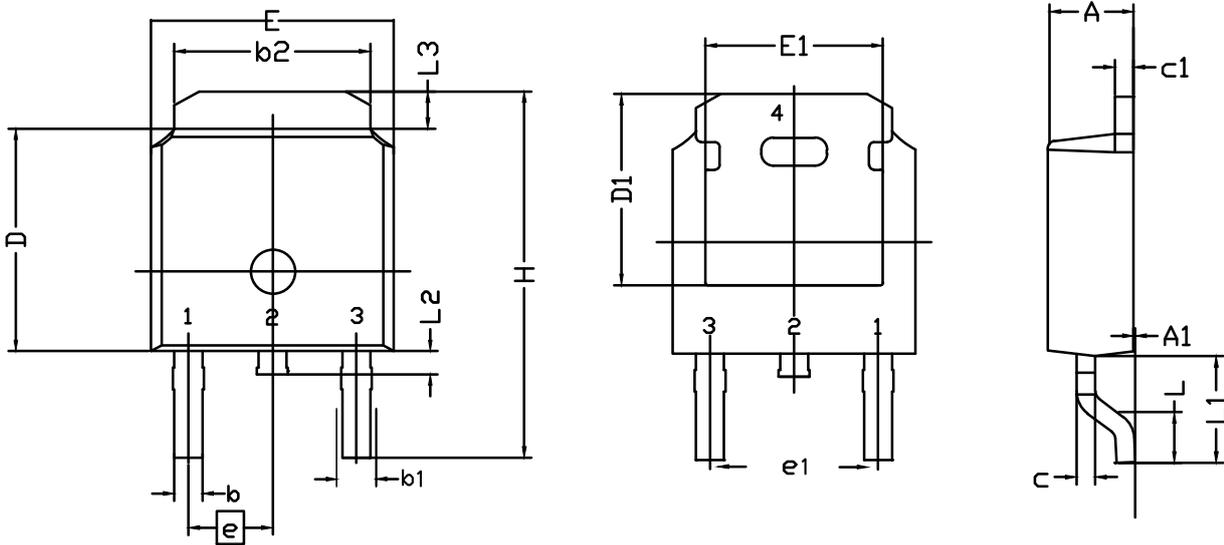
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-40	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-40V, V_{GS}=0V$	---	---	-1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	---	-2.0	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_D=-20A$	---	11	14	m Ω
		$V_{GS}=-4.5V, I_D=-20A$	---	14	16	m Ω
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=-20V, \text{Freq.}=1\text{MHz}$	---	3120	---	pF
C_{oss}	Output Capacitance		---	238	---	
C_{rss}	Reverse Transfer Capacitance		---	226	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=-10V, V_{DD}=-20V, I_D=-20A, R_G=3\Omega$	---	14	---	nS
T_r	Turn-on Rise Time		---	16	---	
$T_{d(off)}$	Turn-off Delay Time		---	36	---	
T_f	Turn-off Fall Time		---	38	---	
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DD}=-20V, I_D=-20A$	---	42	---	nC
Q_{gs}	Gate-Source Charge		---	7	---	
Q_{gd}	Gate-Drain Charge		---	8	---	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	$I_S=-20A, V_{GS}=0V$	---	---	-1.2	V

Note ④: Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤: Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET
Typical Characteristics

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

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Figure 7. V_{DS} Drain-Source Voltage vs Gate Voltage

Figure 8. On-Resistance vs Gate Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Continuous Drain Current vs Temperature

Figure 11. Transient Thermal Response Curve

P-Channel Enhancement Mode MOSFET
TO-252 Package Outline Dimensions


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	2.20	2.30	2.38	E	6.40	6.60	6.731
A₁	0.00	0.10	0.20	E₁	4.40	--	--
b	0.64	0.76	0.89	e	2.286 BSC		
b₁	0.77	0.85	1.14	e₁	4.572 BSC		
b₂	5.00	5.33	5.46	H	9.40	10.00	10.40
c	0.458	0.508	0.610	L	1.40	1.52	1.77
C₁	0.458	0.508	0.620	L₁	--	2.743	--
D	5.98	6.10	6.223	L₂	0.60	0.80	1.01
D₁	5.20	5.25	5.38	L₃	0.90	1.06	1.25